

81. (New) A microelectronic package according to Claim 44 wherein the first microelectronic substrate comprises one of an integrated circuit, a second level microelectronic package, a mating connector substrate or a third level microelectronic package, and wherein the second microelectronic substrate also comprises one of an integrated circuit, a second level microelectronic package, a mating connector substrate or a third level microelectronic package.

82. (New) A microelectronic package according to Claim 52 wherein the first microelectronic substrate comprises one of an integrated circuit, a second level microelectronic package, a mating connector substrate or a third level microelectronic package, and wherein the second microelectronic substrate also comprises one of an integrated circuit, a second level microelectronic package, a mating connector substrate or a third level microelectronic package.

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cont.
83. (New) A microelectronic package according to Claim 65 wherein the first microelectronic substrate comprises one of an integrated circuit, a second level microelectronic package, a mating connector substrate or a third level microelectronic package, and wherein the second microelectronic substrate also comprises one of an integrated circuit, a second level microelectronic package, a mating connector substrate or a third level microelectronic package.

84. (New) A microelectronic package according to Claim 1 wherein the first microelectronic substrate comprises an integrated circuit and wherein the second microelectronic substrate also comprises an integrated circuit.

85. (New) A microelectronic package according to Claim 19 wherein the microelectronic substrate comprises an integrated circuit.

86. (New) A microelectronic package according to Claim 32 wherein the microelectronic substrate comprises an integrated circuit.